AMENDMENTS TO THE SPECIFICATION

Paragraph beginning at page 3, lines 16 is amended as follows:

Aromatic amine curing agents are per se known for semiconductor encapsulants. In particular, Japanese Patent No. 3,238,340 and JP-A 10-158366 disclose amine curing agents analogous to the aromatic amine curing agents of the formulae (1) to (3) used in the present invention. With respect to the molar ratio of epoxy resin to curing agent, JP-A 10-158366 describes that in a curing agent excess situation that the epoxy resin is not more than 0.9 mole per mole of the curing agent, unreacted amino groups are left in excess, resulting in a lowering of humidity resistance and reliability. The inventors have found that when the epoxy resin (A) and the aromatic amine curing agent (B) of formulae (1) to (3) are used in a molar ratio (A)/(B) ~~between 0.7 and 0.9~~ from 0.7/1 to less than 0.9/1, the liquid epoxy resin composition becomes effectively adherent to the surface of silicon chips and especially photosensitive polyimide resins and nitride films, and significantly resistant to thermal shocks, and maintains satisfactory properties under hot humid conditions. The prior art compositions comprising epoxy resin and amine curing agent contain a silane coupling agent as an essential component, which causes voids to generate when the resin compositions are poured or cured for the manufacture of flip chip semiconductor devices. To solve the voiding problem, the composition of the present invention is formulated such that the composition absent a silane coupling agent is highly reliable and effective as an encapsulant especially for large die size semiconductor devices.